

ABSTRACT

A method for packaging a multi-chip module is carried out by connecting a first chip having thereon wafer bumps to lower parts of inner leads of TAB tapes having the inner lead and an outer lead, thereby electrical signals being communicated therebetween; connecting a second chip having thereon wafer bumps to an upper part of the TAB tapes connected to the first chip, thereby electrical signals being communicated therebetween; and executing an encapsulation step, wherein an underfill material is filled in a connecting portion between the TAB tapes and the chips.